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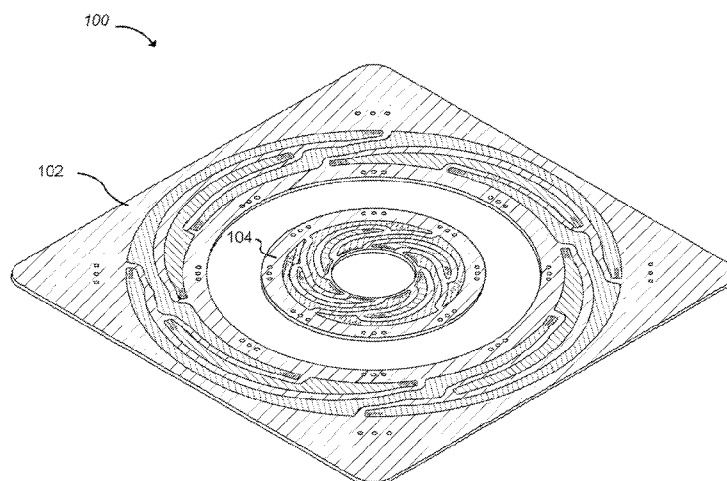


FIG. 1

(57) Abstract: An antenna arrangement in a plasma processing system for providing plasma uniformity across a substrate during substrate processing is provided. The arrangement includes a plurality of circular antenna assemblies. Each circular antenna assembly of the plurality of circular antenna assemblies includes a set of non-circular coils. Each non-circular coil of the set of non-circular coils is offset at a predetermined angle in an azimuthal direction. The arrangement also includes a set of power generators for powering the plurality of circular antenna assemblies.

